ANALOG DEVICES

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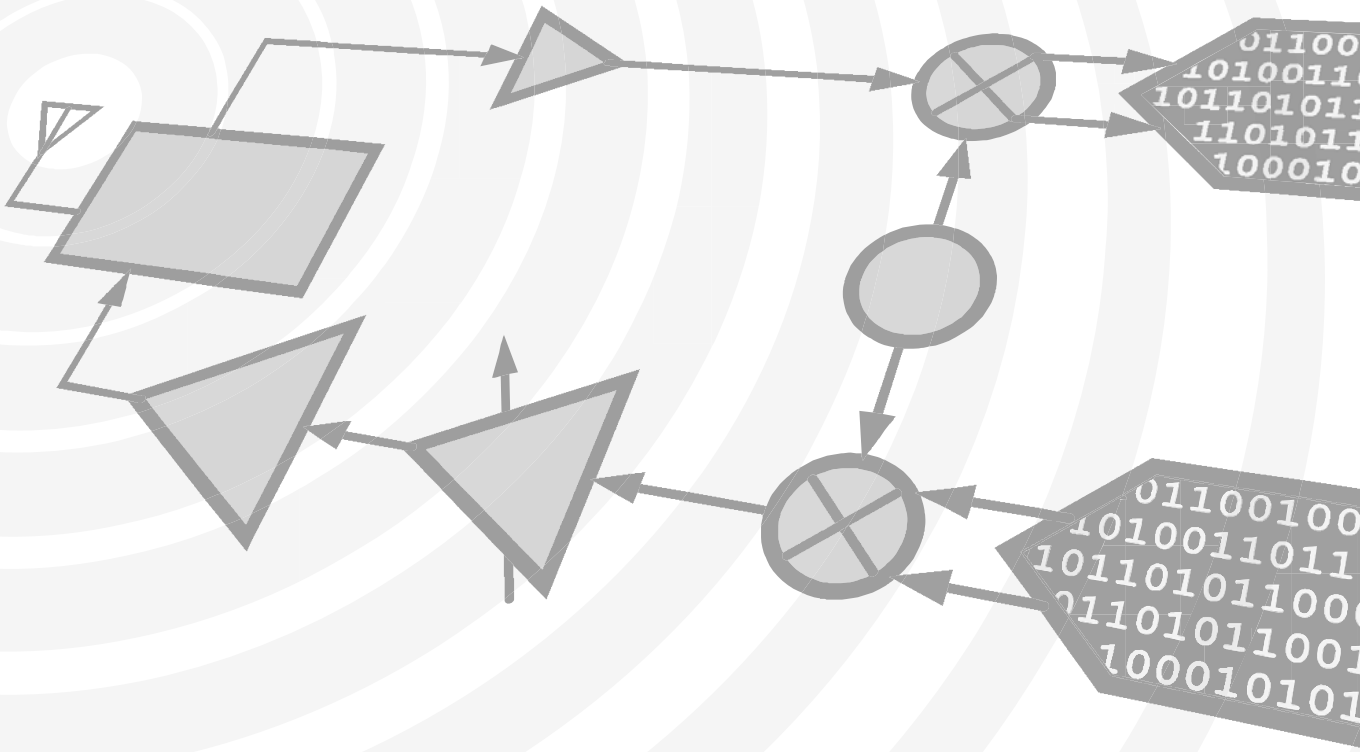
NO CONTENT ON THE ATTACHED DOCUMENT HAS CHANGED



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HMC213AMS8 / 213AMS8E

v02.1210

GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

Typical Applications

The HMC213AMS8(E) is ideal for:

- Base Stations
- PCMCIA Transceivers
- Wireless Local Loop

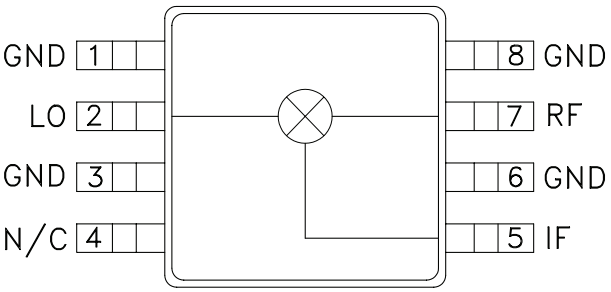
Features

Ultra Small Package: MSOP8

Conversion Loss: 8.5 dB

LO / RF Isolation: 40 dB

Functional Diagram



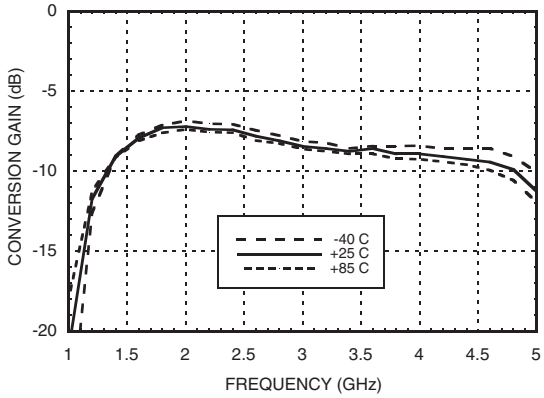
General Description

The HMC213AMS8(E) is a ultra miniature double-balanced mixer in 8 lead plastic surface mount package (MSOP). This passive MMIC mixer is constructed of GaAs Schottky diodes and novel planar transformer baluns on the chip. The device can be used as an upconverter, downconverter, biphase (de)modulator, or phase comparator. The consistent MMIC performance will improve system operation and assure regulatory compliance.

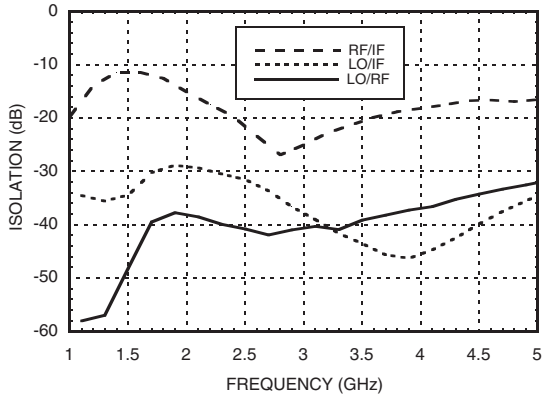
Electrical Specifications, T_A = +25° C, As a Function of LO Drive

Parameter	LO = +13 dBm IF = 100 MHz			LO = +10 dBm IF = 100 MHz			Units
	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency Range, RF & LO	1.5 - 4.5			1.7 - 3.6			GHz
Frequency Range, IF	DC - 1.5			DC - 1.5			GHz
Conversion Loss		8.5	10		9	10.5	dB
Noise Figure (SSB)		8.5	10		9	10.5	dB
LO to RF Isolation	29	40		32	40		dB
LO to IF Isolation	27	35		26	35		dB
IP3 (Input)	16	19		14	18		dBm
1 dB Gain Compression (Input)	7	10		5	8		dBm

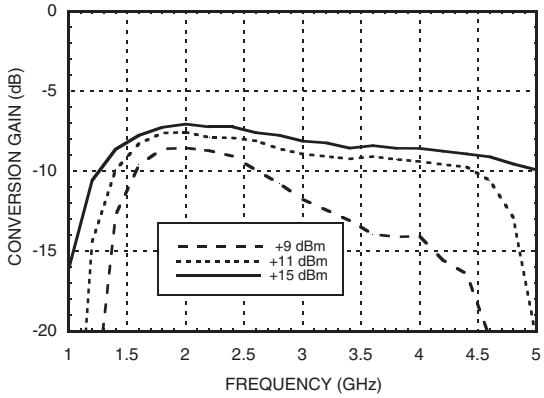
Conversion Gain vs. Temperature @ LO = +13 dBm



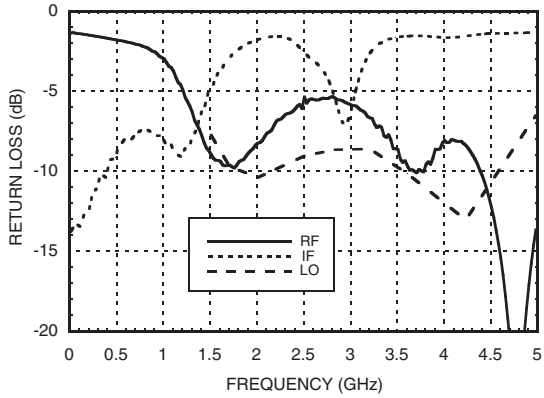
Isolation @ LO = +13 dBm



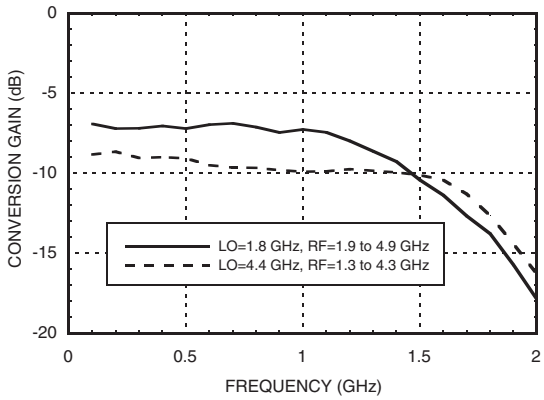
Conversion Gain vs. LO Drive



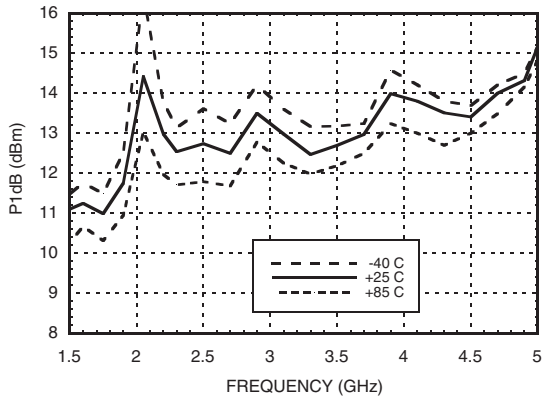
Return Loss @ LO = +13 dBm



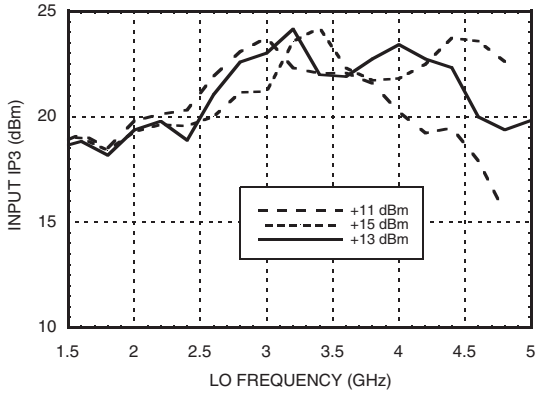
IF Bandwidth @ LO = +13 dBm



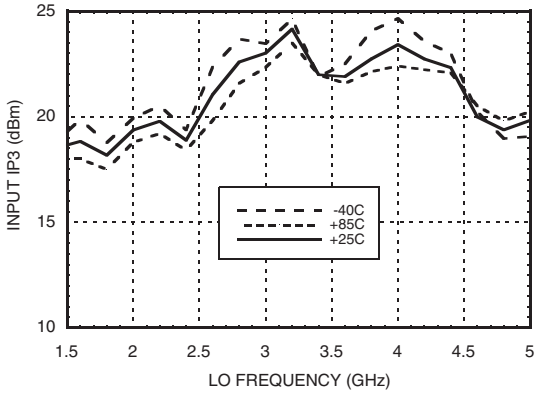
P1dB vs. Temperature @ LO = +13 dBm



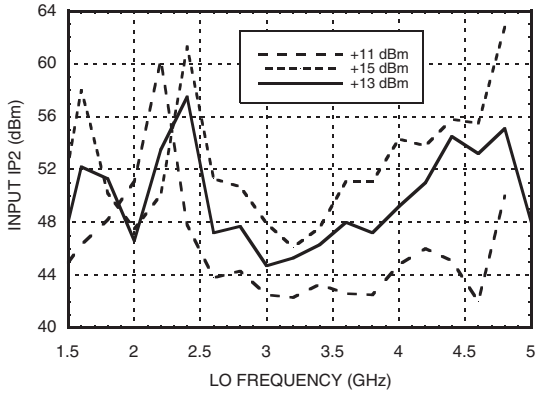
Input IP3 vs. LO Drive



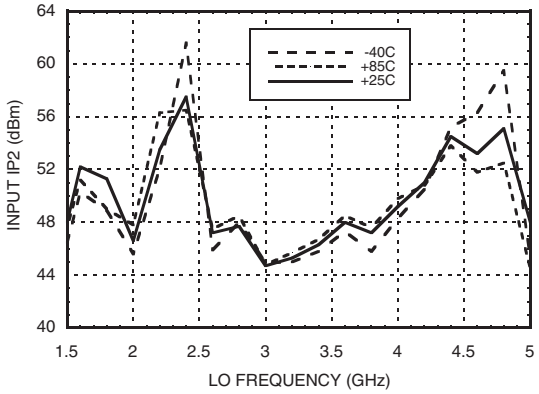
Input IP3 vs. Temperature @ LO = +13 dBm



Input IP2 vs. LO Drive



Input IP2 vs. Temperature @ LO = +13 dBm



MxN Spurious Outputs

	nLO				
mRF	0	1	2	3	4
0	xx	12.7	20.8	19.8	76.2
1	13.4	0	39.8	38.9	56.2
2	73.8	78.2	66.5	82.2	68.8
3	93.8	89.2	92.2	82.4	89.0
4	>105	>105	>105	>105	>105

RF = 3.5 GHz @ -10 dBm
LO = 3.6 GHz @ +13 dBm
All values in dBc below IF power level (-1RF + 1LO)

Harmonics of LO @ RF Port

LO Freq. (GHz)	nLO Spur			
	1	2	3	4
1.5	40	30	62	57
2.0	38	25	55	58
2.5	41	28	34	61
3.0	41	35	36	61
3.5	38	45	52	62
4.0	35	47	55	62
4.5	33	50	65	73
5.0	32	52	68	82

LO = +13 dBm
Values in dBc below input LO level measured at RF Port.

Absolute Maximum Ratings

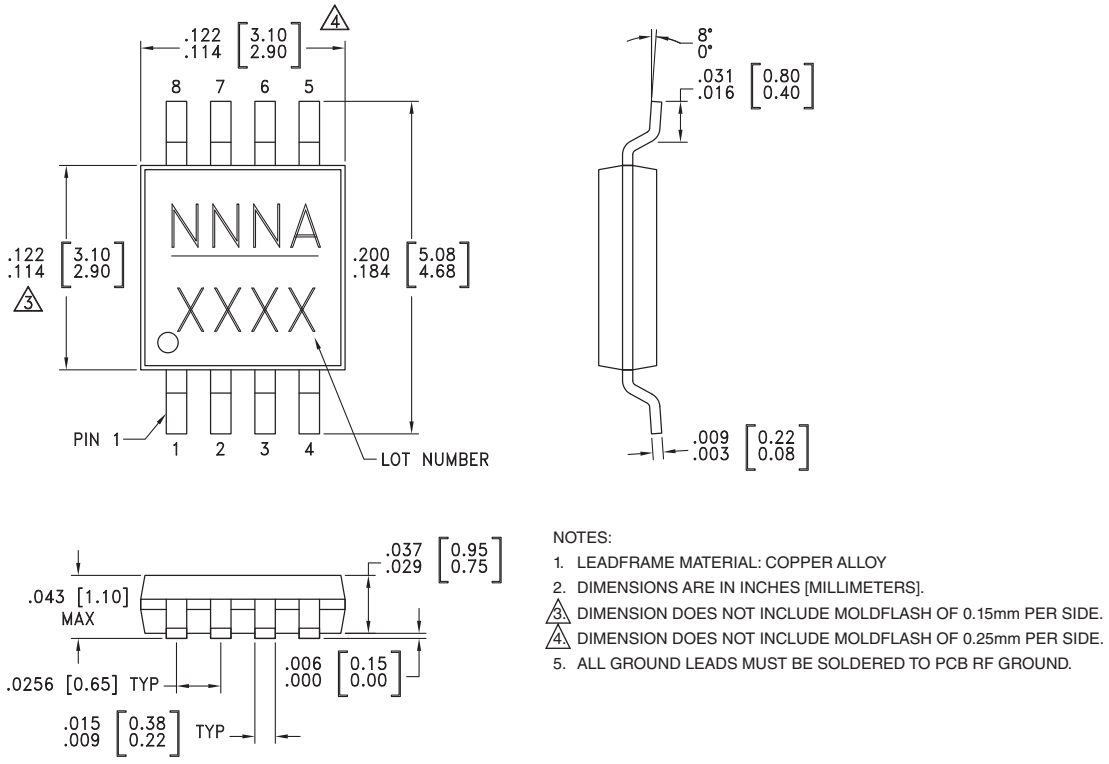
RF / IF Input	+13 dBm
LO Drive	+27 dBm
Continuous Pdiss (T = 85 °C) (derate 10.6 mW/°C above 85 °C)	0.69 W
Thermal Resistance (Channel to package lead)	93.7 °C/W
Junction Temperature	150 °C
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

HMC213AMS8 / 213AMS8E

GaAs MMIC SMT DOUBLE-BALANCED MIXER, 1.5 - 4.5 GHz

Outline Drawing



NOTES:

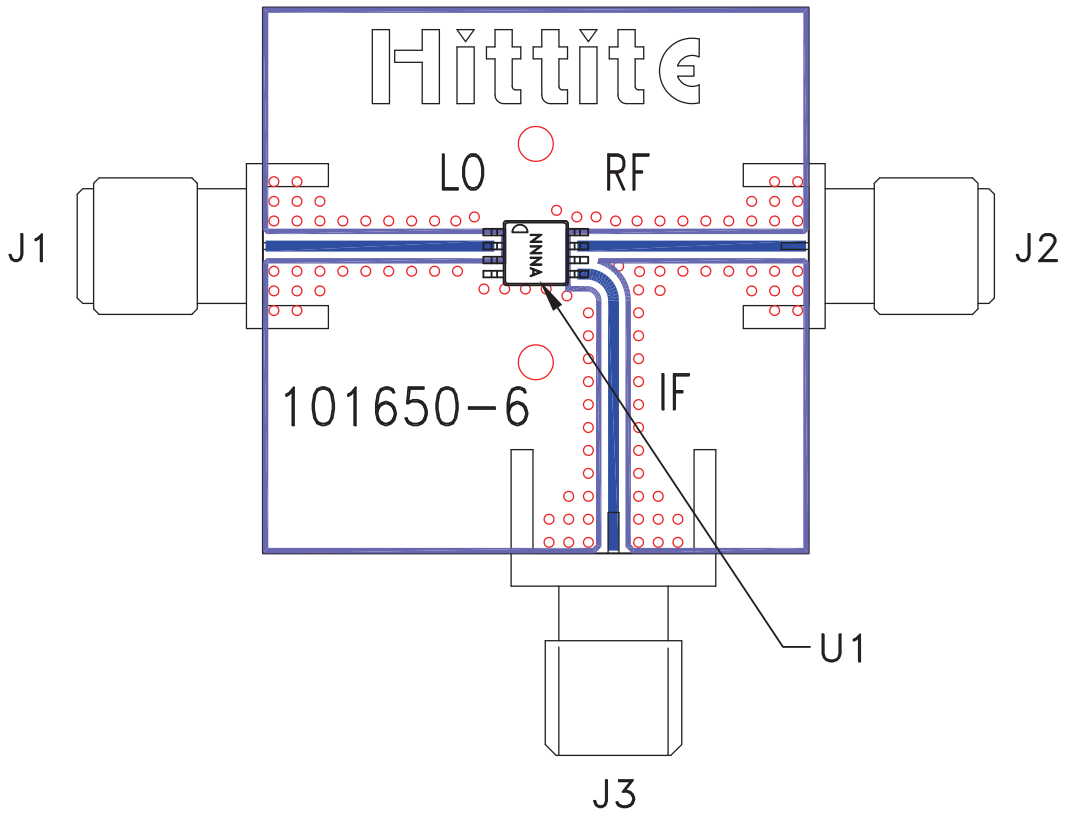
1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC213AMS8	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	213A XXXX
HMC213AMS8E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	213A XXXX

[1] Max peak reflow temperature of 235 °C
[2] Max peak reflow temperature of 260 °C
[3] 4-Digit lot number XXXX

Evaluation PCB



List of Materials for Evaluation PCB 103350 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
U1	HMC213AMS8(E) Mixer
PCB [2]	101650 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.